

August 19, 2026

Nidec Advance Technology to Exhibit Products at THECA Show 2026

Nidec Advance Technology Corporation (“Nidec Advance Technology” or the “Company”) announced today that it will exhibit products at THAILAND ELECTRONICS CIRCUIT ASIA 2026 (THECA), an event scheduled to take place at Bangkok International Trade & Exhibition Centre (BITEC) from Wednesday, August 26 – Friday, August 28, 2026.



Hosted by the Thailand Printed Circuit Association, THECA is an international exhibition for Thailand’s electronics manufacturing industry focused on printed circuit boards (PCB) and printed circuit board assemblies (PCBA).

Nidec Advance Technology’s booth will offer comprehensive quality-control solutions, ranging from inspection jigs’ contacts to internal defect detection, for increasingly dense and complex circuit boards/substrates. The Company’s highly reliable electrical inspection equipment processes high-density and multi-layer substrates effectively, enabling smooth production flows. In addition, with customized high-accuracy jigs securing stable connection and preventing erroneous decisions, the equipment improves the entire production line’s inspection efficiency significantly. Further, at this upcoming exhibition, Nidec Advance Technology will showcase, for the first time ever in Thailand, its state-of-the-art X-ray inspection equipment that can inspect complex electronic components and the inside of substrates vividly.

About THECA:

- Period: Wednesday, August 26 – Friday, August 28, 2026
- Venue: Bangkok International Trade & Exhibition Centre
- Booth: R13
- Official website: <https://thailandelectronicscircuitasia.com/>

Nidec Advance Technology’s main exhibits will include:

- High-speed, CT-type, X-ray inspection equipment for back-drill inspections
- STAR REC® series (conduction/short-circuit inspection equipment for HDI/PCB substrates)
- GATS® series (conduction/short-circuit inspection equipment for semiconductor packages)
- GATS®8360 (conduction/short-circuit inspection equipment for large-size substrates)
- RWi-300MK3 (2D/3D wafer bump inspection equipment)
- AURCA Series (3D/AFVI AI inspection system)
- RSH series (optical 2D/3D inspection equipment for high-density substrates)
- High-precision inspection jigs

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